

In the Claims

Please cancel Claim 2, add Claims 12-14, and amend Claims 1, 3-5, 7, and 9, as follows:

1. (Currently Amended) A method of manufacturing a printed wiring board, ~~the method~~ comprising ~~the steps of~~:

providing a base substrate;

forming a through hole in said base substrate;

forming a first conductor layer on a surface of said through hole and a surface of said base substrate in the vicinity of an opening of said through hole;

filling said through hole where said first conductor layer is formed with a photosensitive resin and forming the photosensitive resin on the opening of said through hole where said first conductor layer is formed and on a surface of said base substrate at least in the vicinity of said opening;

performing a first exposure of said photosensitive resin at a first intensity to expose an upper portion of said photosensitive resin without exposing photosensitive resin located within said through hole;

masking an area substantially above the opening of said through hole;

performing a second exposure of unmasked photosensitive resin at a second intensity different than said first intensity;

removing said exposed photosensitive resin; and

~~exposing said photosensitive resin to light from above said base substrate and developing said photosensitive resin; and~~

forming a second conductor layer ~~after developing the photosensitive resin, said second conductor layer~~ covering the photosensitive resin filled inside said through hole and coupling said second conductor layer ~~coupled~~ to said first conductor layer.

2. (Canceled)

3. (Currently Amended) The method according to claim 1, wherein ~~said step of forming said first conductor layer~~ further comprises ~~the steps of~~:

forming a photoresist on the surface of said base substrate except the surface of said through hole and the surface of said base substrate in the vicinity of the opening of said through hole;

forming said first conductor layer by plating on the surface of said through hole and the surface of said base substrate in the vicinity of the opening of said through hole; and

removing said photoresist after forming said first conductor layer.

4. (Currently Amended) The method according to claim 1 further comprising ~~a step of forming a circuit pattern on the surface of said base substrate after developing~~ removing said photosensitive resin.

5. (Currently Amended) The method according to claim 4, wherein ~~said step of forming a circuit pattern~~ is carried out simultaneously with ~~said step of forming said second conductor layer~~.

6. (Original) The method according to claim 1, wherein said photosensitive resin is a positive photosensitive resin.

7. (Currently Amended) The method according to claim 1, further comprising ~~the steps of~~: forming an insulating layer on the surface of said base substrate so as to cover said second conductor layers-forming a via hole in said insulating layer, said via hole extending to reach said second conductor layer; and forming a via conductor covering a surface of said insulating layer at least in the vicinity of an opening of said via hole and coupled to said second conductor layer.
8. (Original) The method according to claim 1, wherein said first conductor layer comprises copper and said second conductor layer comprises copper.
9. (Currently Amended) The method according to claim 1, wherein the first and second exposures comprise an ultraviolet photolithographic process.
10. (Original) The method according to claim 1, wherein said base substrate comprises a copper-clad laminate board.
11. (Original) The method according to claim 1, wherein said first conductor layer forms a through hole conductor and said second conductor layer forms a capped conductor.
12. (New) The method according to claim 1, wherein said photosensitive resin filled inside said through hole is heat cured.

13. (New) The method according to claim 1, wherein said second intensity is greater than said first intensity.

14. (New) The method according to claim 1, wherein said exposed photosensitive resin is removed through development.